□ MN102H730F, MN102H73G, MN102H73K

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Туре	MN102H730F	MN102H73G (under development)	MN102H73K (under development)		
ROM (×8-bit)	External	128 K	256 K		
RAM (×8-bit)	10 K	10 K	12 K		
Package	TQFP128-P-1414B *Lead-free	TQFP128-P-1414A *Lead-free			
Minimum Instruction Execution Time	With main clock operated	58 ns (at 3.0 V to 3.6 V, 34 MHz)			
Interrupts	 RST pin • Watchdog • NMI pin • Timer counter 0 to 9 underflow • Timer counter 10 to 14 underflow • Timer counter 10 to 14 compare capture A • Timer counter 10 to 14 compare capture B • ATC ch.0 to 1 transfer finish • ETC ch.0 to 1 transfer finish • External 0 to 7 • Serial ch.0 to 4 transmission • Serial ch.0 to 4 reception • A/D conversion finish 				
Timer Counter	s	1/2 of system clock (BOSC) frequency; t system clock (BOSC) underflow of timer counter 0	underflow of timer counter 8; TM0IO pi		
	Timer counter 1 : 8-bit × 1 Clock source				
	Timer counter 2 : 8-bit × 1 Clock source	1/2 of system clock (BOSC) frequency; t imer counter 1 output underflow of timer counter 2	underflow of timer counter 8; TM2IO pi		
	t	1/2 of system clock (BOSC) frequency; t imer counter 2 output inderflow of timer counter 3	underflow of timer counter 8; TM3IO pi		
	s	1/2 of system clock (BOSC) frequency; t system clock (BOSC) inderflow of timer counter 4	underflow of timer counter 9; TM4IO p		
	Timer counter 5 : 8-bit × 1 Clock source	1/2 of system clock (BOSC) frequency; t imer counter 4 output underflow of timer counter 5	underflow of timer counter 9; TM5IO p		
	t	1/2 of system clock (BOSC) frequency; t imer counter 5 output inderflow of timer counter 6	underflow of timer counter 9; TM6IO p		
	Timer counter 7 : 8-bit × 1 Clock source	1/2 of system clock (BOSC) frequency; v imer counter 6 output underflow of timer counter 7	underflow of timer counter 9; TM7IO p		
	Timer counter 8 : 8-bit × 1 Clock source ······ 1	1/2 of system clock (BOSC) frequency; s 1/4 of system clock (XI) frequency; TM8 underflow of timer counter 8	-		

Timer Counte	r (Continue)	Timer counter 9 : 8-bit × 1
Timer Counter (Continue)		Clock source
		Interrupt source underflow of timer counter 9
		Timer counter 10 : 16-bit × 1 (timer output, event count, input capture, PWM output, 2-phase encoder input) Clock source underflow of timer counter 8, 9; TM10IOB pin; 1/2 of system clock (BOSC) frequency; 2-phase encode of TM10IOA pin/TM10IOB pin (1 ×, 4 ×)
		Interrupt source underflow of timer counter 10; timer counter 10 compare capture A; timer counter 10 compare capture B
		Timer counter 11 : 16-bit × 1 (timer output, event count, input capture, PWM output, 2-phase encoder input) Clock source underflow of timer counter 8, 9; TM11IOB pin; 1/2 of system clock (BOSC) frequency; 2-phase encode of TM11IOA pin/TM11IOB pin (1 ×, 4 ×) Interrupt source underflow of timer counter 11; timer counter 11 compare capture A;
		timer counter 11 compare capture B
		Timer counter 12 : 16-bit × 1 (timer output, event count, input capture, PWM output, 2-phase encoder input) Clock source underflow of timer counter 8, 9; TM12IOB pin; 1/2 of system clock (BOSC) frequency; 2-phase encode of TM12IOA pin/TM12IOB pin (1 ×, 4 ×)
		Interrupt source underflow of timer counter 12; timer counter 12 compare capture A; timer counter 12 compare capture B
		Timer counter 13 : 16-bit × 1 (timer output, event count, input capture, PWM output, 2-phase encoder input) Clock source underflow of timer counter 8, 9; TM13IOB pin; 1/2 of system clock (BOSC) frequency; 2-phase encode of TM13IOA pin/TM13IOB pin (1 ×, 4 ×)
	Interrupt source underflow of timer counter 13; timer counter 13 compare capture A; timer counter 13 compare capture B	
		Timer counter 14 : 16-bit × 1 (timer output, event count, input capture, PWM output, 2-phase encoder input) Clock source underflow of timer counter 8, 9; TM14IOB pin; 1/2 of system clock (BOSC) frequency; 2-phase encode of TM14IOA pin/TM14IOB pin (1 ×, 4 ×)
	Interrupt source underflow of timer counter 14; timer counter 14 compare capture A; timer counter 14 compare capture B	
Serial Interface		Serial 0, 1 : 8-bit × 1 (transfer direction of MSB / LSB selectable, transmission / reception of 7, 8-bit length) Clock source
		Serial 2, 3 : 8-bit × 1 (transfer direction of MSB / LSB selectable, transmission / reception of 7, 8-bit length) Clock source
		UART \times 4 (common use with serial 0 to 3)
		$I^2C \times 2$ (common use with serial 1,3; single master)
Multiply-and-A	ccumulate	16-bit sign × 16-bit sign + 40-bit sign
I/O Pins	I/O	104 • Common use : 59 (use of full address, address data separate 16-bit mode) • Common use : 76 (use of address 16-bit, address data separate 8-bit mode)
A/D Inputs		10-bit \times 12-ch. (with S/H)
D/A Outputs		8-bit \times 4-ch.
PWM		16-bit \times 5-ch. (timer counter 10 to 14)
ICR		16-bit × 5-ch. (timer counter 10 to 14)
OCR		16-bit \times 5-ch. (timer counter 10 to 14)
Notes		Address / data separate bus interface; 8 / 16-bit bus width selectable; SRAM interface

See the next page for electrical characteristics, pin assignment and support tool.

Electrical Characteristics

Supply current

Deremeter	Symbol	Orandiklar	Limit			11
Parameter		Condition		typ	max	Unit
Operating supply current	IDDopr	VI = VDD or VSS, output open		60+10 α *		
		$f=34\ \text{MHz}$, VDD = 3.3 V	00+10α**		mA	
Supply current at STOP	IDDS	Pin with pull-up resistor is open	70		μΑ	
		all other input pins and Hi-Z state input/output		70		
Supply current at HALT	IDDH	pins are simultaneously applied VDD or VSS level			30+10α*	mA
		f = 34 MHz, VDD = 3.3 V, output open		50+100°		

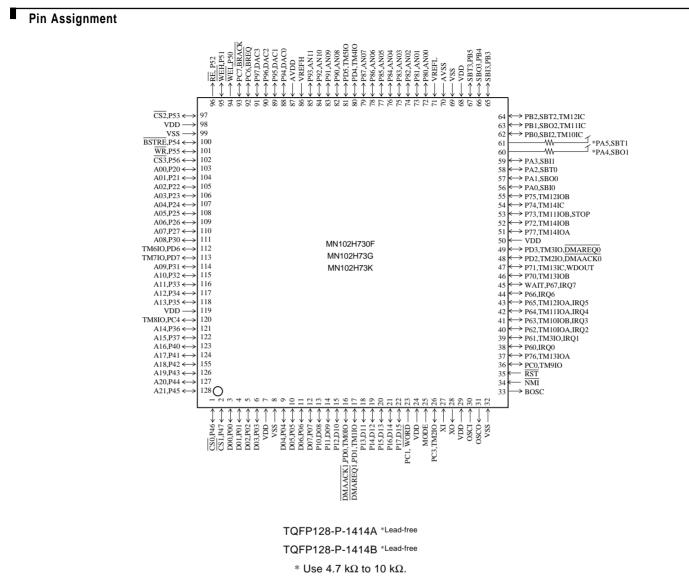
 $(Ta = -40^{\circ}C \text{ to } +85^{\circ}C \text{ , } VDD = AVDD = 3.3 \text{ V} \text{ , } VSS = AVSS = 0 \text{ V})$

 \ast " α " depends on products .

 $MN102H73G/73K/730F\ \alpha=0$

MN102HF73G $\alpha = 1$

MN102HF73K $\alpha = 2$



Support Tool

In-circuit Emulator	PX-ICE102H73-128P1414		
Flash Memory Built-in Type	Туре	MN102HF73G, MN102HF73K	
	ROM (× 8-bit)	128 K / 256 K	
	RAM (× 8-bit)	10 K / 12 K	
	Minimum instruction execution time	58 ns (at 3.0 V to 3.6 V, 34 MHz)	
	Package	TQFP128-P-1414B *Lead-free	

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